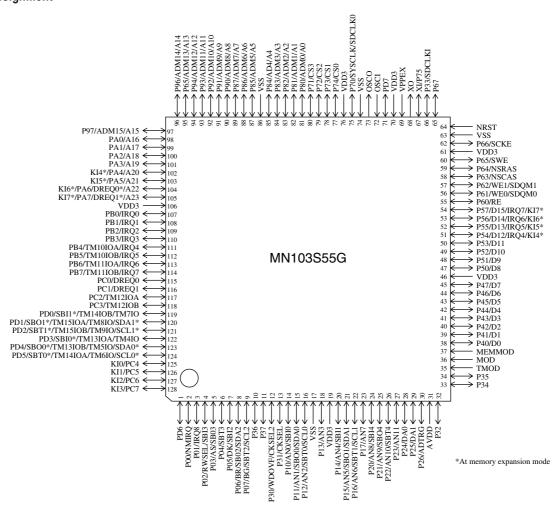
■ MN103S55G

Туре	MN103S55G (under development)
Command ROM (×64-bit)	128 K-byte
Data RAM (×32-bit)	16 K-byte
Package	LQFP128-P-1818C *Pb-free
Minimum Instruction Execution Time	25.0 ns (at 2.7 V to 3.6 V, 40 MHz)
Interrupts	• RESET • IRQ × 9 • NMI • Timer × 30 • SIF × 10 • I ² C × 3 • KEY • DMA × 12 • WDT • A/D • System error
Timer Counter	8-bit timer × 10 Reload-down count Cascade connection possible (usable as a 16-bit to 32-bit timer)
	16-bit timer × 6 Up-down count Input capture function PWM generating function Compare/capture register 2-ch.
	Time base timer \times 1, Free run counter
	Watchdog timer \times 1
DMA Controller	Number of channels: 4 Unit of transfer: 8/16/32 bits Max. Transfer cycles: 65535 Staring factor: external interrupt, timer factor, serial transmission/reception factor, I ² C transmission/reception factor, external transmission request factor, A/D conversion finish, software factor Transfer method: 2-bus cycle transfer Adressing modes: fixed, increment, decrement Transfer modes: word transfer, burst transfer, intermittent transfer
Serial Interface	UART/synchronous/multi-master I ² C interface selective: 3 UART/synchronous interface selective: 2
I/O Pins I/O	109 • Common use
A/D Inputs	10-bit × 12-ch.
D/A Inputs	8-bit × 2-ch.
Electrical Characteristics	T.B.D.

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Pin Assignment



LQFP128-P-1818C*Pb-free

SupportTool

On-board Development Tools PX-ODB103S-O	
Flash Memory Built-in Type Type MN103SF55G (under development)	
Command ROM (× 64-bit) 128 K-byte	
Data RAM (× 32-bit) 16 K-byte	
Minimum instruction execution time 25.0 ns (at 2.7 V to 3.6 V, 40 MHz)	
Package LQFP128-P-1818C *Pb-free	

MAF00013AEM Panasonic

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